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(12) **United States Design Patent**
Wang

(10) **Patent No.:** **US D566,689 S**

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(54) **HEADPHONE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/277,915**

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(51) **LOC (8) Cl.** **14-01**

(52) **U.S. Cl.** **D14/206**

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D14/144, 147, 165, 192, 198, 205–206, 223;
D29/112; 2/209.3, 410; 181/129–130; 379/430,
379/440, 433.01; 381/370–371, 374, 376,
381/377–379; D21/483, 516–517

See application file for complete search history.

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Primary Examiner—Paula A. Greene

(57) **CLAIM**

The ornamental design for a headphone, as shown.

DESCRIPTION

FIG. 1 is a front elevational view of a headphone showing my new design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a left side view thereof;

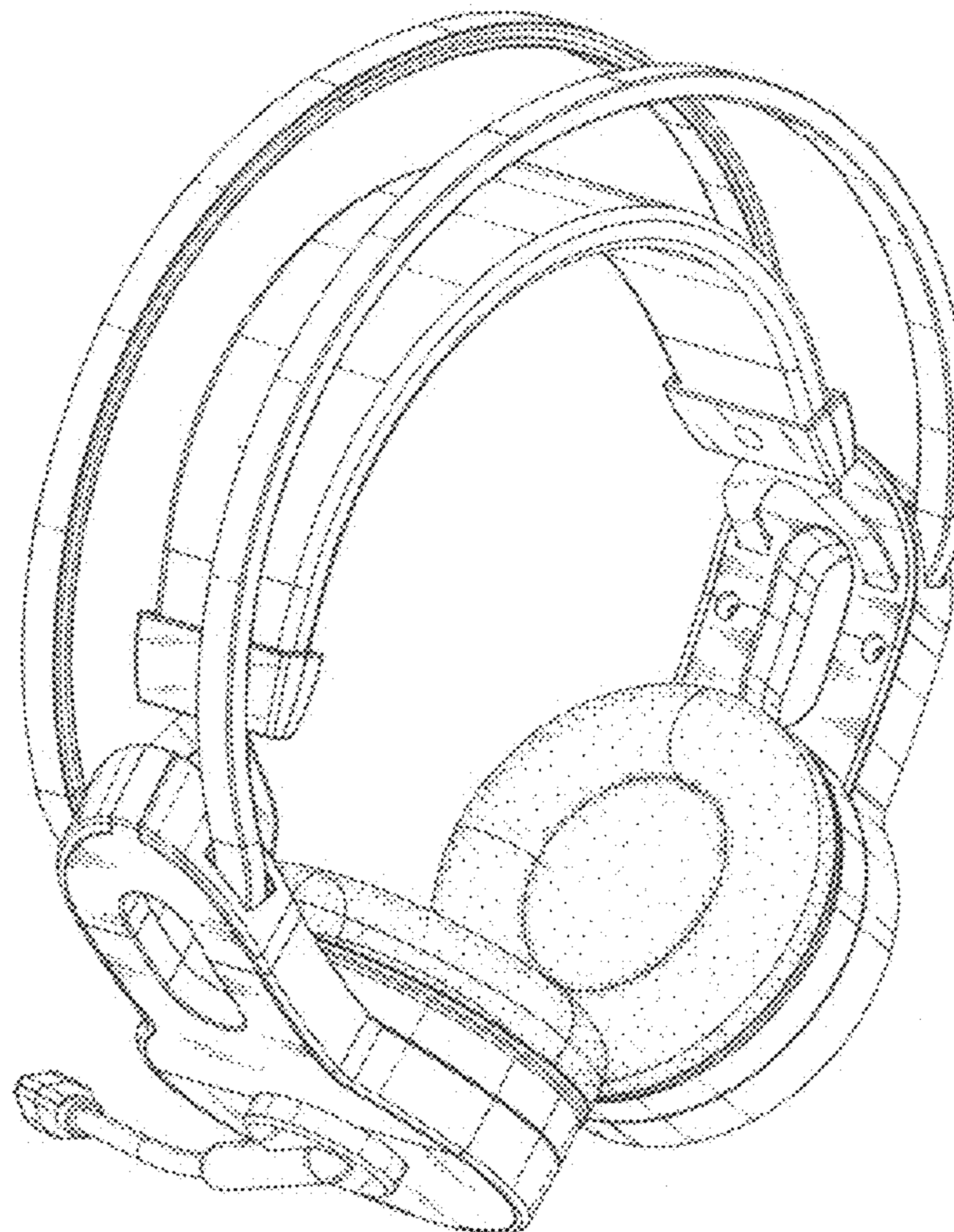
FIG. 4 is a right side view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof; and,

FIG. 7 is a perspective view thereof.

1 Claim, 5 Drawing Sheets



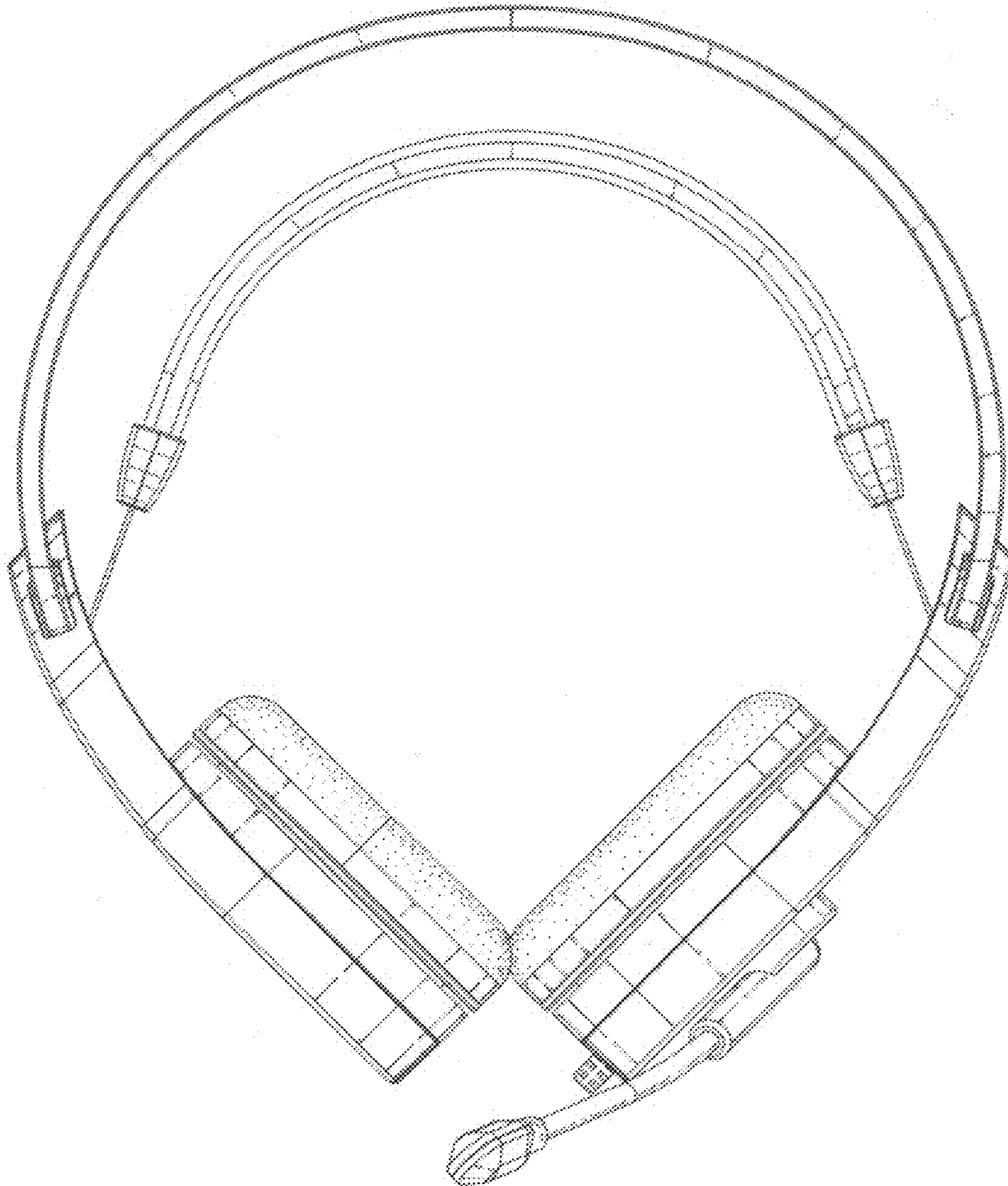


Fig. 1

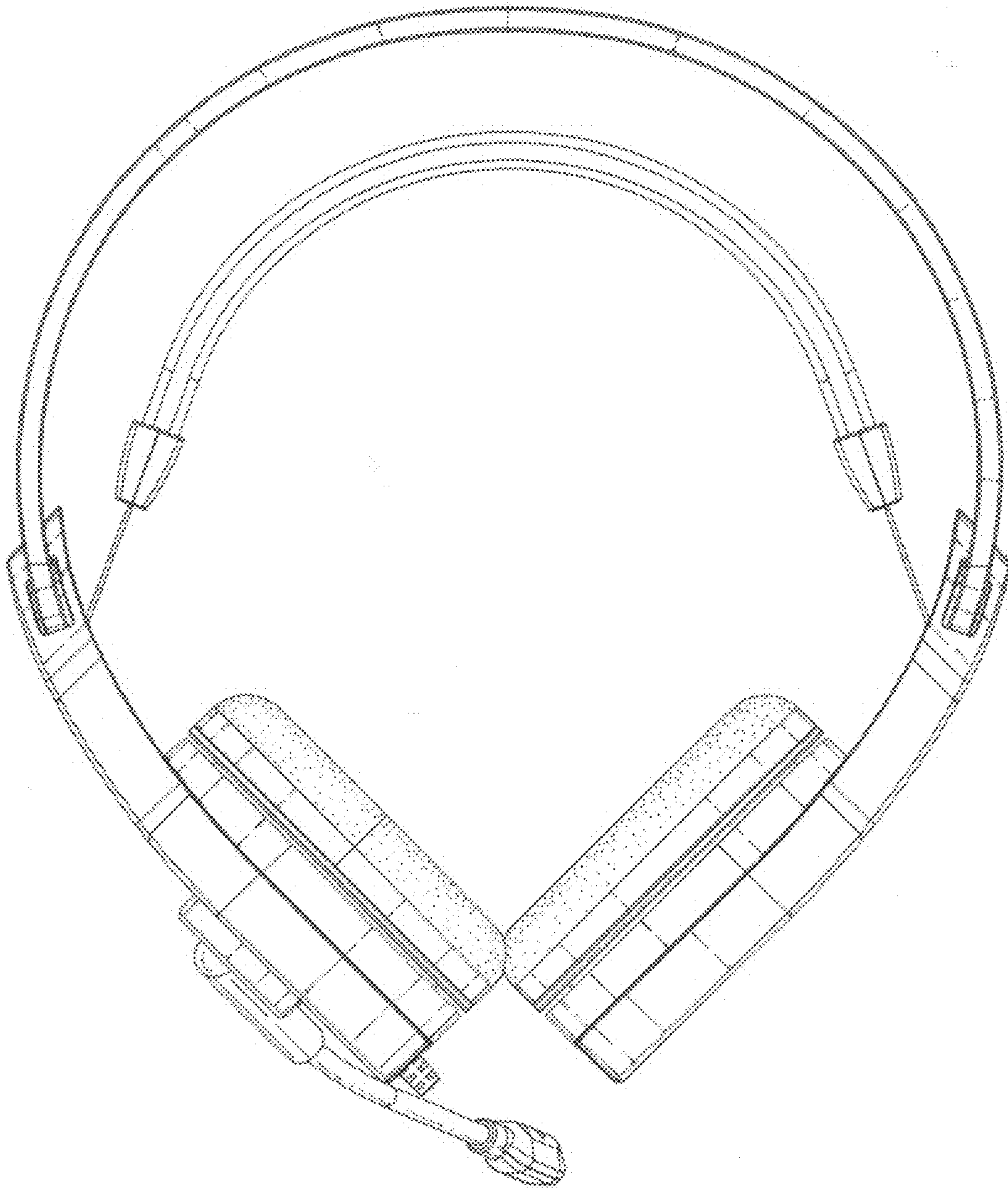


Fig. 2

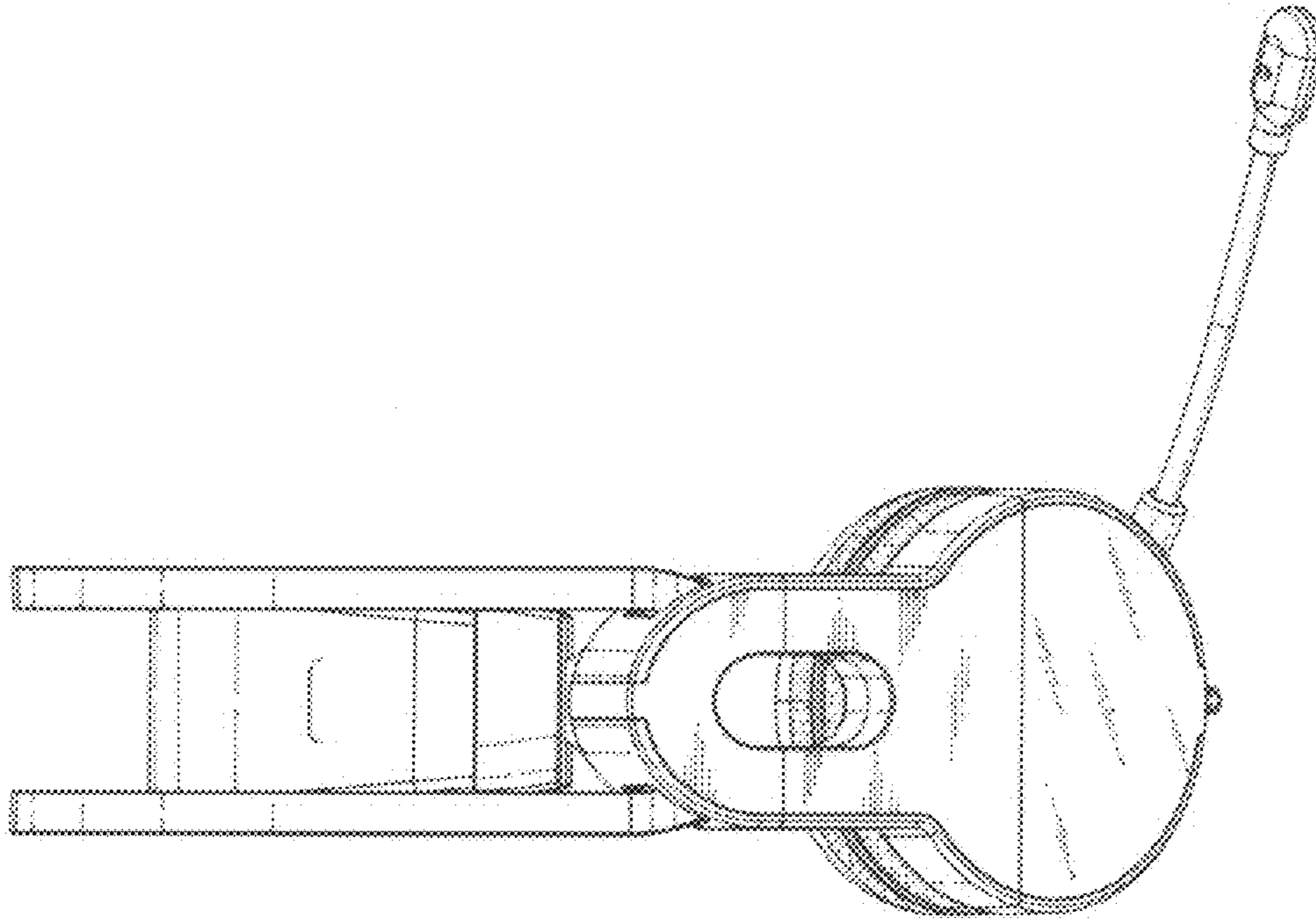


Fig. 4

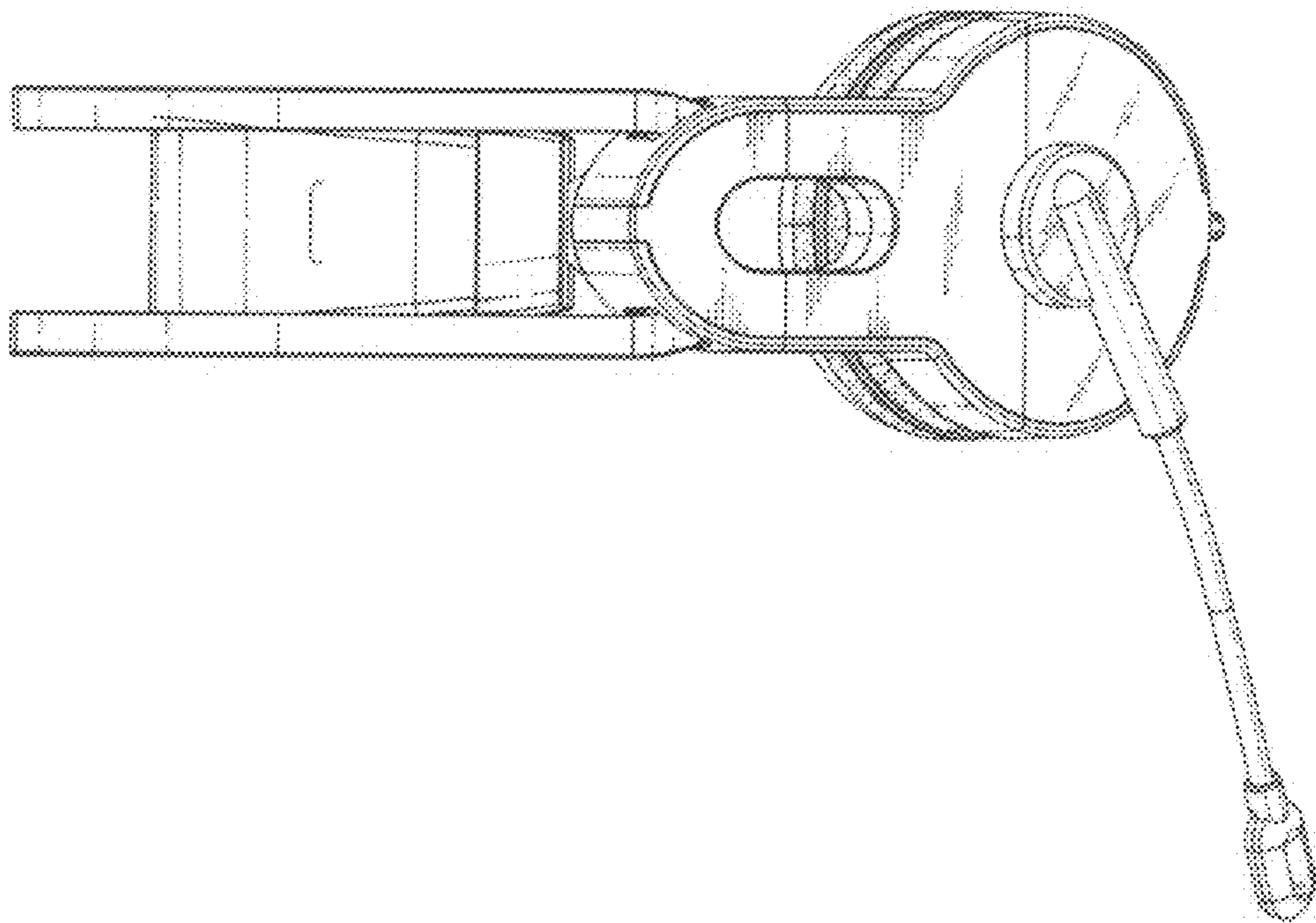


Fig. 3

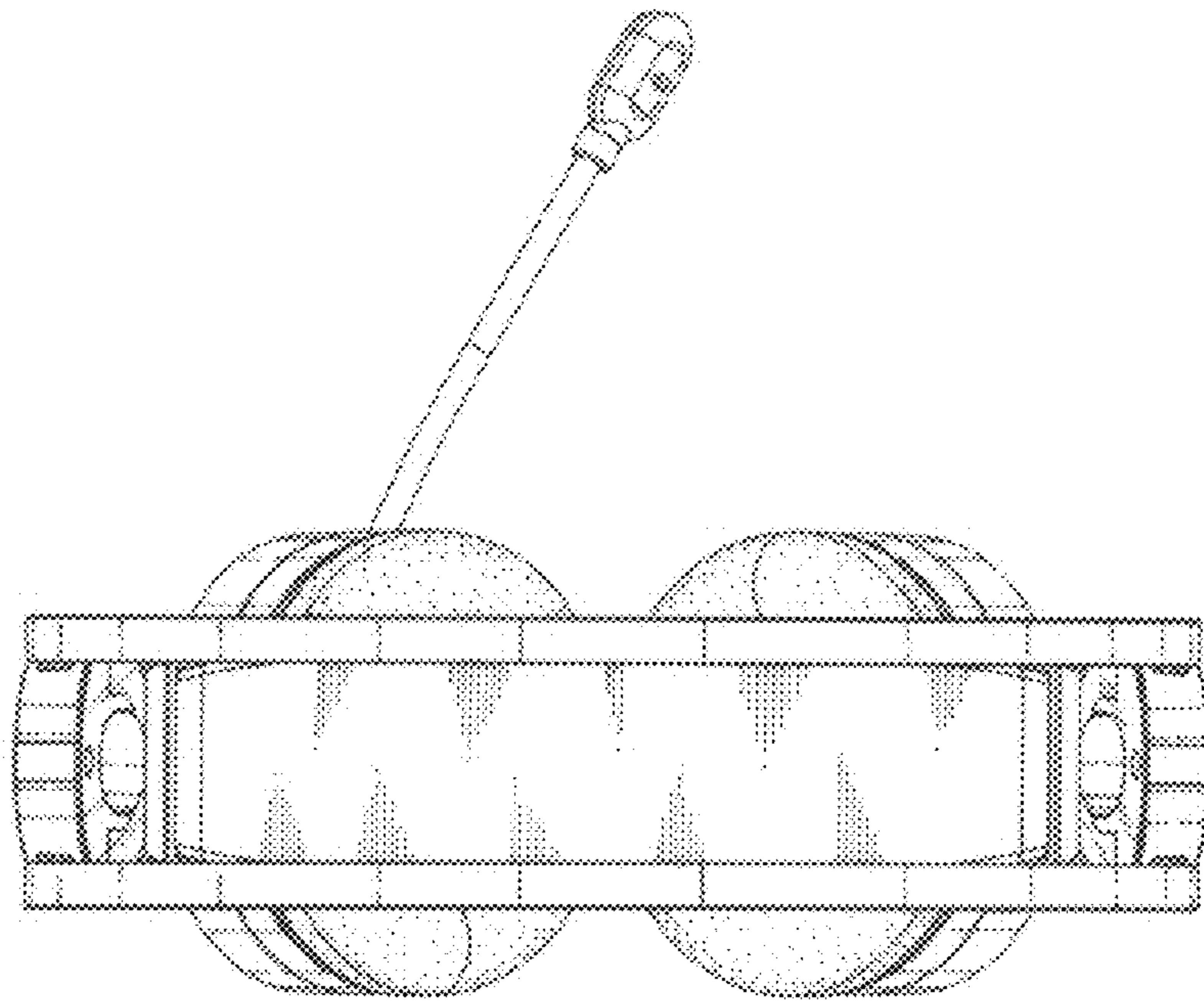


Fig. 5

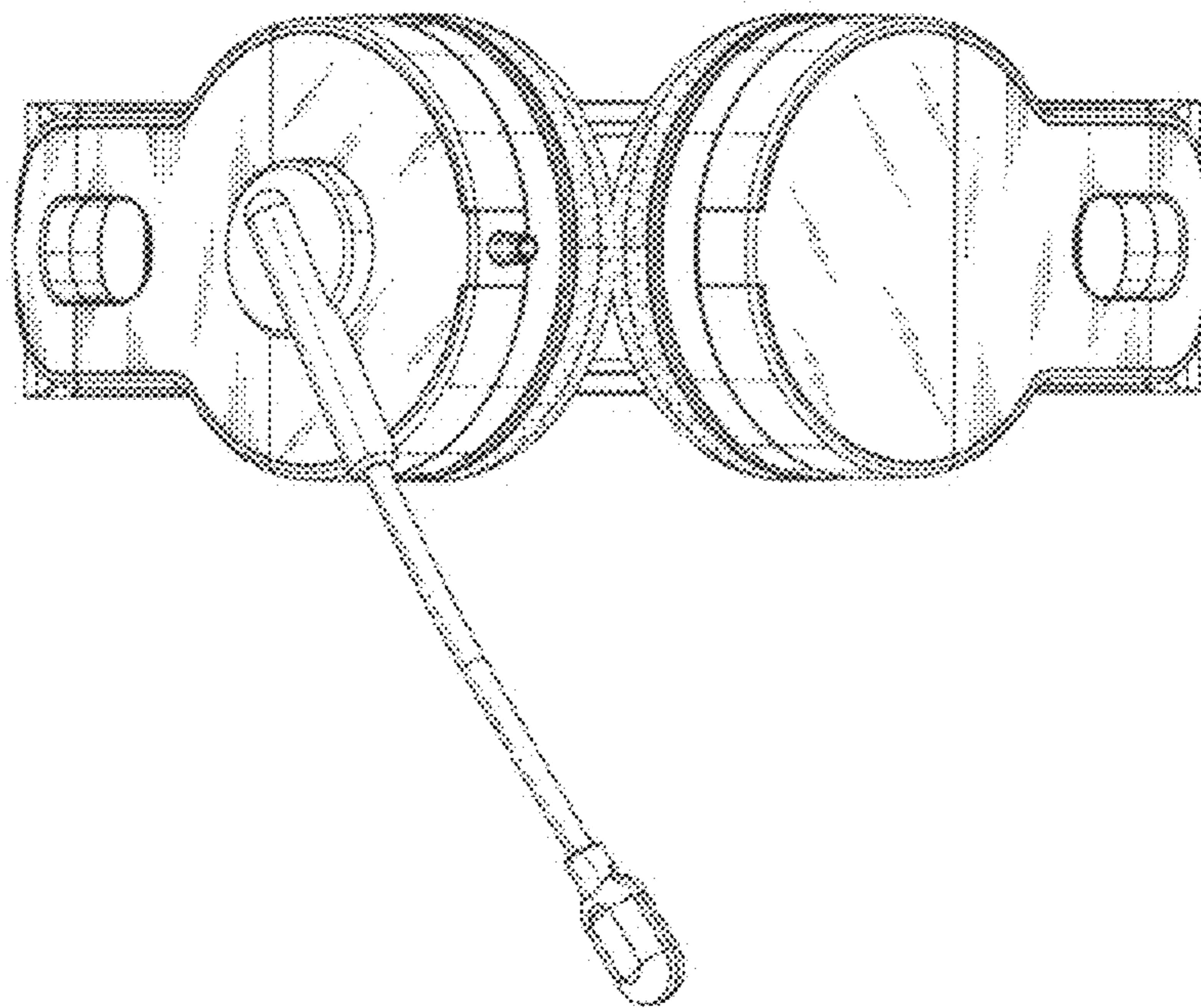


Fig. 6

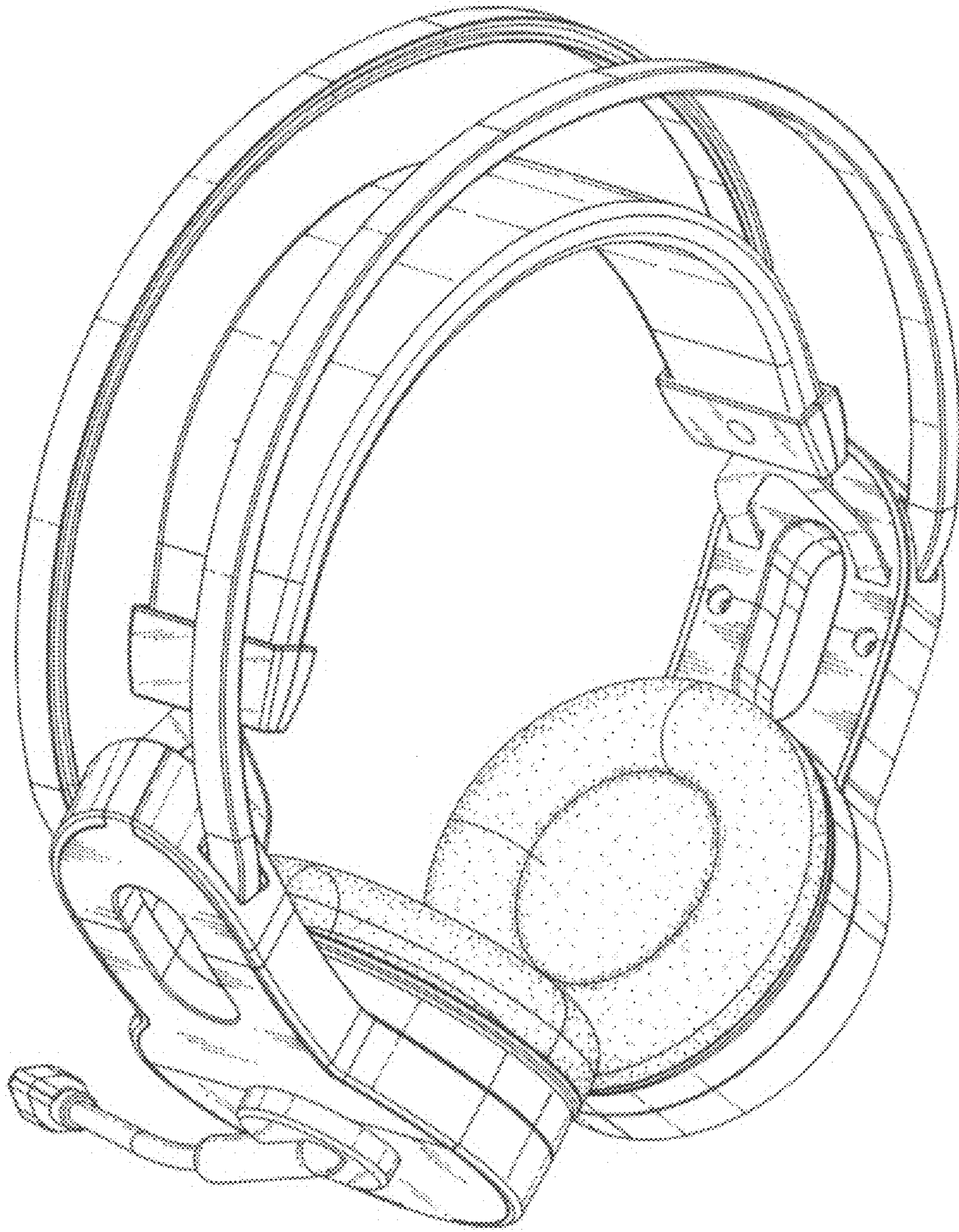


Fig. 7